



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D  * : Required Field

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2019-01-10
<b>Company Unique ID</b>	NL 008751171801		
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Contact Phone *</b>	Refer to Supplier Comment section	<b>Contact Email *</b>	Refer to Supplier Comment section
<b>Authorized Representative *</b>	Rossana Bonaccorso	<b>Representative Title</b>	ADG MD Champion
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**


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Legal Statement		
<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>
		Standard

**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STL260N4LF7	BXER*OL48R82	A	3068	2019-01-10
Amount	UoM	Unit type	ST ECOPACK Grade	
100.00	mg	Each	ECOPACK2	
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant ( in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NA	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFN	5-6-0.8	12	Flat	
Comment	Power FLAT 5x6 8L SINGLE			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-March 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : ELV directive : 2000/53/EC amended 2017/2096 _November 2017	
Query	Response
1 - Product(s) meets EU ELV requirements without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
Exemption Id.	Description
8e	Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead)

QueryList : California Prop65 list, dated 25th May 2018			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.10	Die	1000
Lead	8.23	Soft solder	82290

QueryList : REACH-27th June 2018				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				FALSE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
Lead	1000 ppm	8.23	Soft solder	82290
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				FALSE
CategoryLevel_Name	CategoryLevel_Threshold	Amount in Embedded Article / Homogeneous Material (mg)	Application - Article / Homogeneous Material	ppm in Article /Homogeneous Material
Lead	1000 ppm	8.23	Soft solder	925022

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	BXER*OL48R82						
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)	
Die	M-011 Other inorganic materials	2.929	mg	supplier	die	Silicon (Si)	7440-21-3		2.483	mg	847730	24830	
				supplier	metallization	Aluminium (Al)	7429-90-5		0.164	mg	55992	1640	
				supplier	metallization	Nickel (Ni)	7440-02-0		0.041	mg	13998	410	
				supplier	metallization	Silver (Ag)	7440-22-4		0.024	mg	8194	240	
				supplier	metallization	Titanium (Ti)	7440-32-6		0.018	mg	6144	180	
				supplier	metallization	Tungsten (W)	7440-33-7		0.041	mg	13998	410	
				supplier	Passivation	Silicon Nitride	12033-89-5		0.026	mg	8877	260	
				supplier	Passivation	Silicon Oxide	7631-86-9		0.040	mg	13657	400	
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.005	mg	1707	50	
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.059	mg	20143	590	
				supplier	back side metallization	Vanadium (V)	7440-62-2		0.004	mg	1366	40	
				supplier	back side metallization	Silver (Ag)	7440-22-4		0.024	mg	8194	240	
				Leadframe	M-004 Copper and its alloys	49.734	mg	supplier	alloy	Copper (Cu)	7440-50-8		48.971
supplier	alloy	Iron (Fe)	7439-89-6						0.049	mg	985	490	
supplier	alloy	Iron Phosphide (FeP)	26508-33-8						0.015	mg	302	150	
Soft solder	Solder	8.896	mg	supplier	metallization	Silver (Ag)	7440-22-4		0.699	mg	14055	6990	
				supplier	JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	8.229	mg	925022	82290
				supplier	solder	Tin (Sn)	7440-31-5		0.222	mg	24955	2220	
Bonding wires	M-011 Other inorganic materials	0.116	mg	supplier	solder	Silver (Ag)	7440-22-4		0.445	mg	50023	4450	
				supplier	wire	Gold (Au)	7440-57-5		0.116	mg	1000000	1160	
Encapsulation	M-011 Other inorganic materials	29.742	mg	supplier	mold compound	Silica, vitreous	80676-86-0		27.541	mg	925997	275410	
				supplier	mold compound	epoxy resin	85954-11-6		1.190	mg	40011	11900	
				supplier	mold compound	phenol resin	26834-02-6		0.892	mg	29991	8920	
Connections coating	Solder	0.149	mg	supplier	mold compound	carbon black	1333-86-4		0.119	mg	4001	1190	
				supplier	solder alloy	Tin (Sn)	7440-31-5		0.149	mg	1000000	1490	
Clip	M-004 Copper and its alloys	8.434	mg	supplier	alloy	Copper ( Cu)	7440-50-8		8.434	mg	1000000	84340	